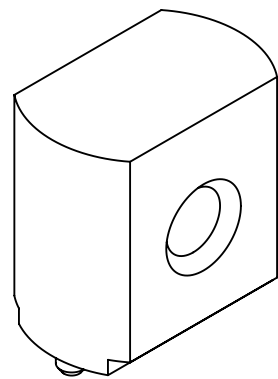
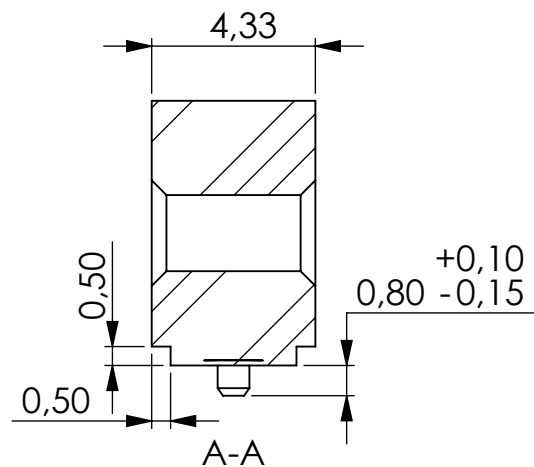
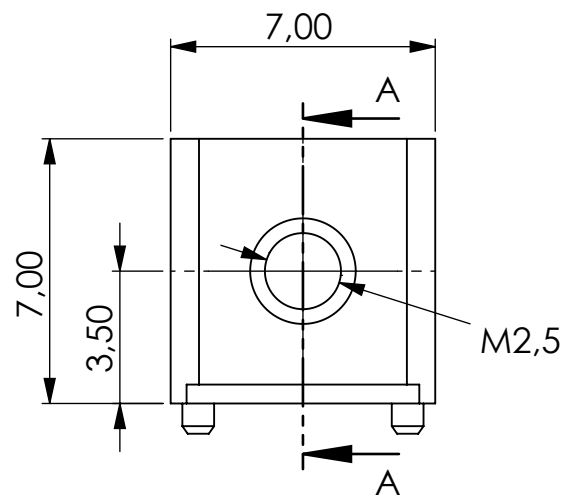
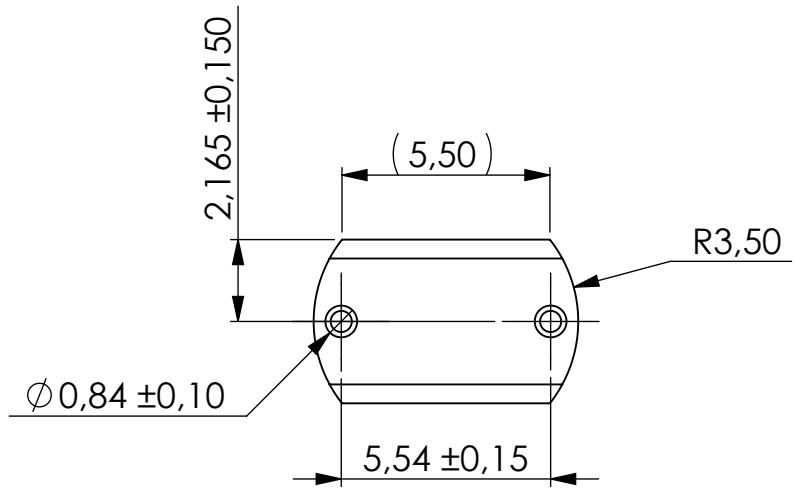
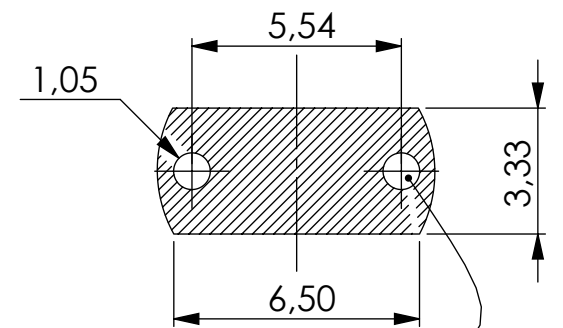


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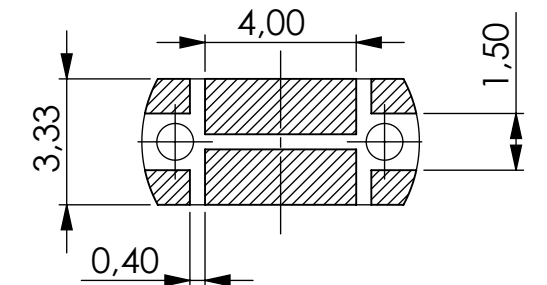


Recommended Solder Pad:

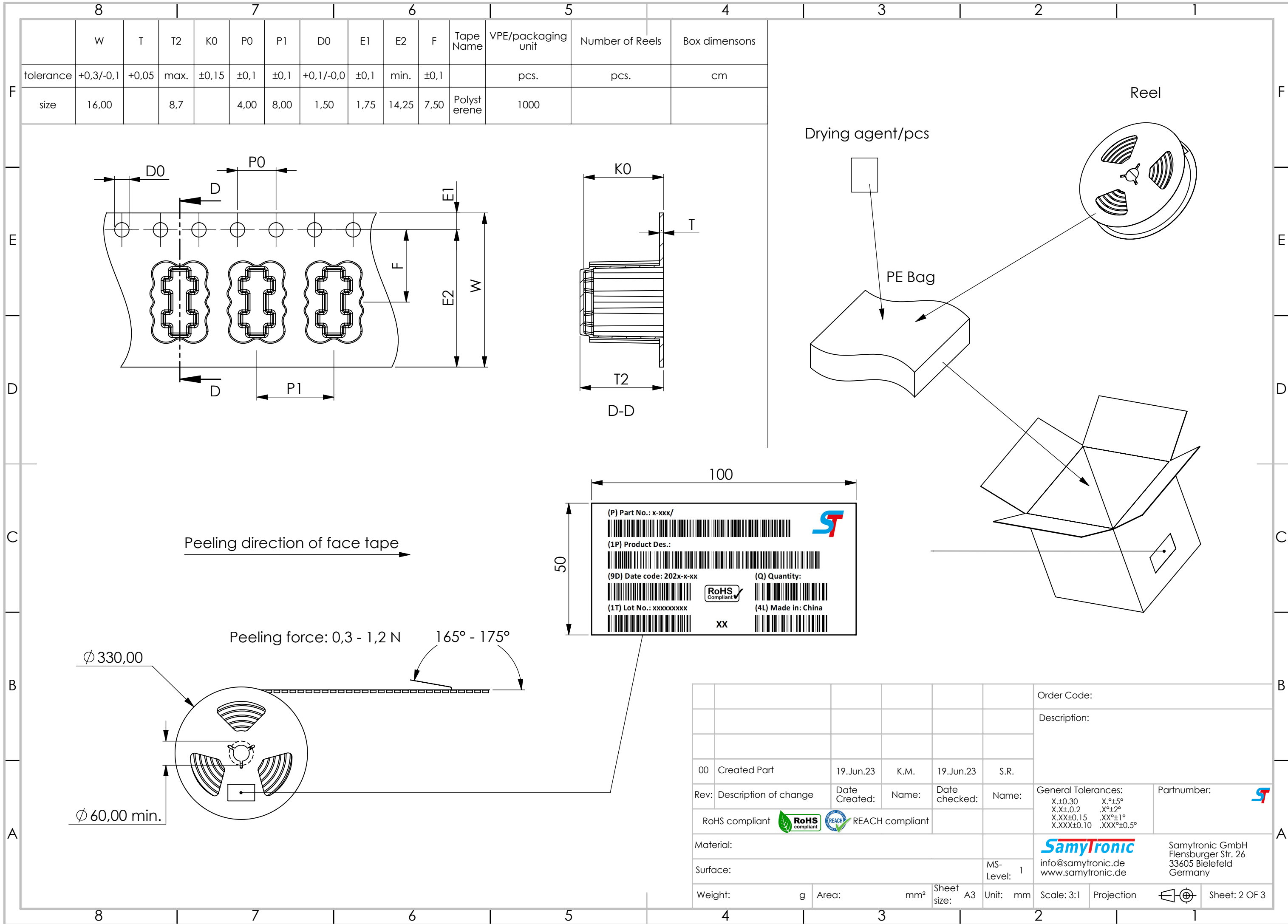


If as a current-carrying element, then not plated.
If used as a mechanical element, then plated for better mechanical support.

Recommended Stencil Masks:



						Order Code: SMTGTRA2570MTJ	
						Description:	
						SMT Terminals right angled M2.5 with Pin, Tape and Reel	
00	Created Part	19.Jun.23	K.M.	19.Jun.23	S.R.		
Rev:	Description of change	Date Created:	Name:	Date checked:	Name:	General Tolerances:	Partnumber:
						X.±0.30 X.°±5° X.X±0.2 .X°±2° X.XX±0.15 .XX°±1° X.XXX±0.10 .XXX°±0.5°	108-002
RoHS compliant				REACH compliant			
Material: Steel							
Surface: Tin						MS-Level: 1	
Weight: 1.41 g		Area: mm²		Sheet size: A3	Unit: mm	Scale: 5:1	Projection
							Sheet: 1 OF 3

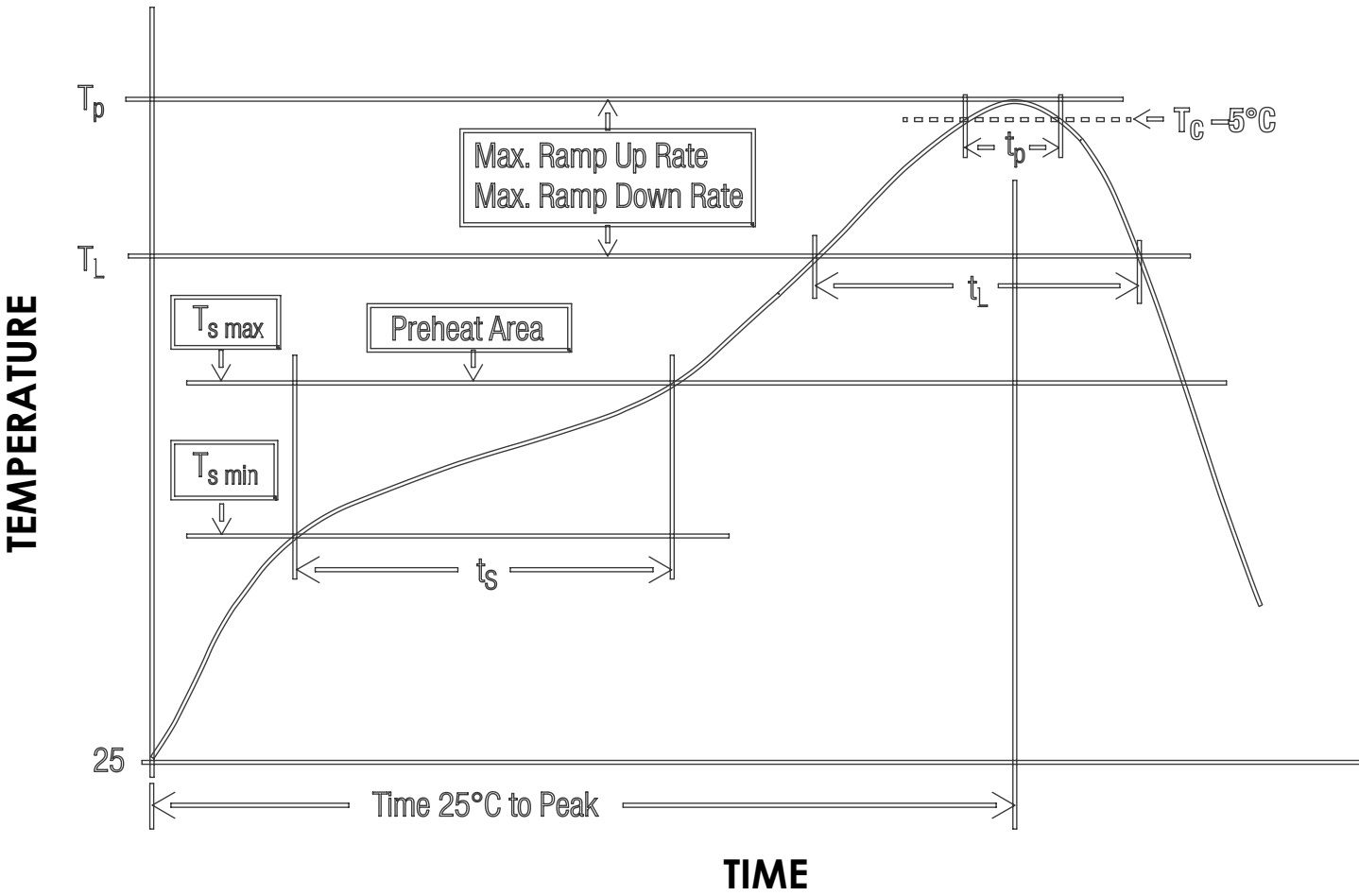


CLASSIFICATION REFLOW PROFILE

Classification Reflow Soldering Profile:

Profile Feature	Value
Preheat Temperature Min (T_{smin}) ¹⁾	150 °C
Preheat Temperature Max (T_{smax})	200 °C
Preheat Time (t_s) from(T_{smin} to T_{smax})	60 - 120 seconds
Ramp-up rate (T_L to T_P)	3 °C/ second max.
Liquidous temperature (T_L)	217 °C
Time (t_L) maintained above T_L	60 - 150 seconds
Peak package body temperature (T_P)	$T_P \leq T_C$ see table below
Time (t_P)* within 5 °C of actual peak temperature	20 - 30 seconds
Ramp-down rate (T_P to T_L)	6 °C / second max.
Time 25 °C to peak temperature	8 minutes max.

1) refer to IPC/JEDEC J-STD-020E



Package Classification Reflow Temperature (T_C):

Properties	Volume mm³ < 350	Volume mm³ 350 - 2000	Volume mm³ >2000
PB-Free Assembly Package Thickness < 1.6 mm ¹⁾	260 °C	260 °C	260 °C
PB-Free Assembly Package Thickness 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
PB-Free Assembly Package Thickness ≥ 2.5 mm	250 °C	245 °C	245 °C

1) refer to IPC/JEDEC J-STD-020E

						Order Code:	
						Description:	
00	Created Part	19.Jun.23	K.M.	19.Jun.23	S.R.		
Rev:	Description of change	Date Created:	Name:	Date checked:	Name:	General Tolerances:	Partnumber:
						X.±0.30	X.°±5°
						X.X±0.2	.X°±2°
						X.XX±0.15	.XX°±1°
						X.XXX±0.10	.XXX°±0.5°
RoHS compliant			REACH compliant				
Material:							
Surface:					MS-Level: 1	Samytronic GmbH Flensburger Str. 26 33605 Bielefeld Germany	
Weight: g		Area: mm²		Sheet size: A3	Unit: mm	Scale: 3:1	Projection 
							Sheet: 3 OF 3